

In the Title of the Invention:

Please replace the title of the invention with the following to correct a typographical error:

APPARATUS FOR ETCHING SEMICONDUCTOR SAMPLES AND A SOURCE FOR PROVIDING A GAS BY ~~SUBLIMATION~~ SUBLIMATION THERETO

In the Specification:

Please replace the paragraph beginning on Page 1, Line 12 with the following to correct typographical errors:

The present invention relates to an apparatus for etching semiconductor samples. More particularly, the present invention relates to an apparatus for etching semiconductor samples having a variable volume expansion chamber and to an apparatus having two or more fixed volume expansion chambers, wherein either apparatus may include an apparatus for detecting the end point of the etching process. The present invention also relates to an improved source for providing a gas by ~~sUBLIMATION~~ sUBLIMATION, in particular a source for providing a gas by ~~sUBLIMATION~~ sUBLIMATION to an apparatus described herein.

REMARKS

Notice of Allowance of the above-referenced patent application was issued by the United States Patent and Trademark Office on January 8, 2004. In response, Applicants filed formal drawings on January 21, 2004 and forwarded their Issue Fee payment on March 22, 2004.

Applicants have since discovered typographical errors in the title of the application and in the first page of the specification which they would like to correct prior to printing. Applicants respectfully request that the above-noted corrections be made prior to the grant of Letters Patent.